

- ★ Green Device Available
- ★ Super Low Gate Charge
- ★ Excellent CdV/dt effect decline
- ★ Advanced high cell density Trench technology
- ★ 100% EAS Guaranteed

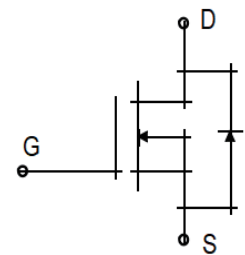
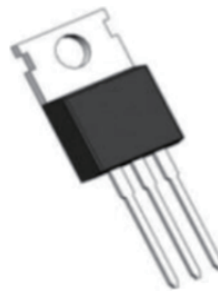
Product Summary

| BVDSS | R _{DS(on)} | I _D |
|-------|---------------------|----------------|
| 150V | 9.5mΩ | 120A |

Description

The 120N15T is the high cell density trenched N-ch MOSFETs, which provide excellent R_{DS(on)} and gate charge for most of the synchronous buck converter applications.

The 120N15T meet the RoHS and Green Product, requirement 100% EAS guaranteed with full function reliability approved.

TO-220 Pin Configuration

Absolute Maximum Ratings

| Symbol | Parameter | Value | Unit |
|-----------------------------------|--|-----------------------|-------|
| V _{DS} | Drain-Source Voltage | 150 | V |
| V _{GS} | Gate-Source Voltage | ±20 | V |
| I _D | Continuous Drain Current | T _C =25°C | 120 |
| | | T _C =100°C | 56 |
| I _{DM} | Pulsed Drain Current ¹ | 352 | A |
| EAS | Single Pulse Avalanche Energy ² | 204.8 | mJ |
| P _D | Total Power Dissipation | T _C =25°C | 178.6 |
| T _J , T _{STG} | Operating Junction and Storage Temperature Range | -55 to 150 | °C |

Thermal Data

| Symbol | Parameter | Typ. | Max. | Unit |
|------------------|--|------|------|------|
| R _{θJA} | Thermal Resistance Junction-Ambient ¹ | --- | 52 | °C/W |
| R _{θJC} | Thermal Resistance Junction-Case ¹ | --- | 0.7 | °C/W |

Electrical Characteristics ($T_J = 25^\circ\text{C}$ unless otherwise specified)

| Symbol | Parameter | Test Conditions | Min. | Typ. | Max. | Unit | | |
|--|---|--|---------------------------------|------|-----------|------------|---|----|
| Static Characteristics | | | | | | | | |
| $V_{(BR)DSS}$ | Drain-Source Breakdown Voltage | $V_{GS} = 0V, I_D = 250\mu A$ | 150 | - | - | V | | |
| I_{GSS} | Gate-body Leakage Current | $V_{DS} = 0V, V_{GS} = \pm 20V$ | - | - | ± 100 | nA | | |
| I_{DSS} | Zero Gate Voltage Drain Current | $T_J = 25^\circ\text{C}$ | - | - | 1 | μA | | |
| | | $T_J = 100^\circ\text{C}$ | - | - | 100 | | | |
| $V_{GS(th)}$ | Gate-Threshold Voltage | $V_{DS} = V_{GS}, I_D = 250\mu A$ | 2 | 3 | 4 | V | | |
| $R_{DS(on)}$ | Drain-Source On-Resistance ⁴ | $V_{GS} = 10V, I_D = 20A$ | - | 9.5 | 11.5 | m Ω | | |
| g_{fs} | Forward Transconductance ⁴ | $V_{DS} = 10V, I_D = 20A$ | - | 69 | - | S | | |
| Dynamic Characteristics ⁵ | | | | | | | | |
| C_{iss} | Input Capacitance | $V_{DS} = 75V, V_{GS} = 0V, f = 1\text{MHz}$ | - | 3310 | - | μF | | |
| C_{oss} | Output Capacitance | | - | 268 | - | | | |
| C_{rss} | Reverse Transfer Capacitance | | - | 9.4 | - | | | |
| R_g | Gate Resistance | $f = 1\text{MHz}$ | - | 3.2 | - | Ω | | |
| Switching Characteristics ⁵ | | | | | | | | |
| Q_g | Total Gate Charge | $V_{GS} = 10V, V_{DS} = 75V, I_D = 20A$ | - | 45 | - | nC | | |
| Q_{gs} | Gate-Source Charge | | - | 15 | - | | | |
| Q_{gd} | Gate-Drain Charge | | - | 8.5 | - | | | |
| $t_{d(on)}$ | Turn-On Delay Time | $V_{GS} = 10V, V_{DD} = 75V, R_G = 3\Omega, I_D = 20A$ | - | 16 | - | ns | | |
| t_r | Rise Time | | - | 12 | - | | | |
| $t_{d(off)}$ | Turn-Off Delay Time | | - | 30 | - | | | |
| t_f | Fall Time | | - | 18 | - | | | |
| t_{rr} | Body Diode Reverse Recovery Time | | - | 76 | - | | | |
| Q_{rr} | Body Diode Reverse Recovery Charge | | $I_F = 20A, dI/dt = 100A/\mu s$ | - | 182 | | - | nC |
| Drain-Source Body Diode Characteristics | | | | | | | | |
| V_{SD} | Diode Forward Voltage ⁴ | $I_S = 20A, V_{GS} = 0V$ | - | - | 1.2 | V | | |
| I_S | Continuous Source | $T_C = 25^\circ\text{C}$ | - | - | 120 | A | | |

Notes:

1. Repetitive rating, pulse width limited by junction temperature $T_J(\text{MAX}) = 150^\circ\text{C}$
2. The EAS data shows Max. rating. The test condition is $V_{DD} = 50V, V_{GS} = 10V, L = 0.4\text{mH}, I_{AS} = 32A$.
3. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper, The value in any given application depends on the user's specific board design.
4. The data tested by pulsed, pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$.
5. This value is guaranteed by design hence it is not included in the production test.

Typical Performance Characteristics

Figure 1: Output Characteristics

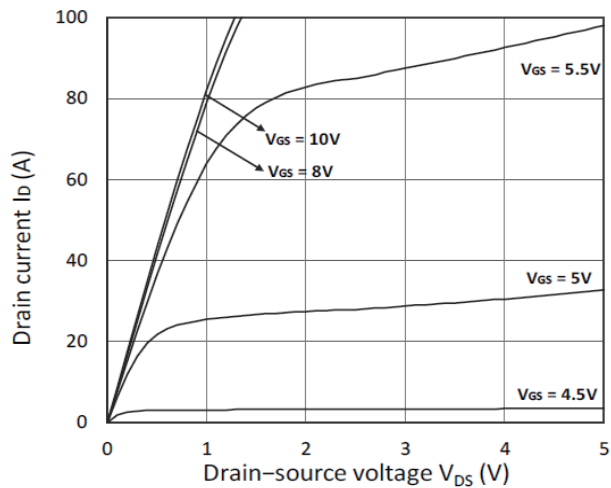


Figure 2: Typical Transfer Characteristics

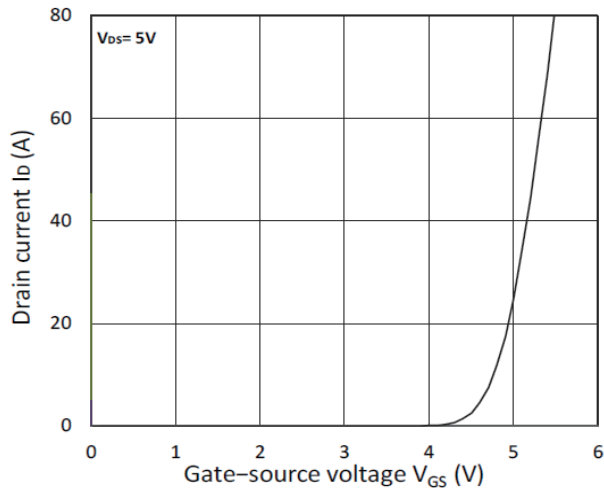


Figure 3: Forward Characteristics of Reverse

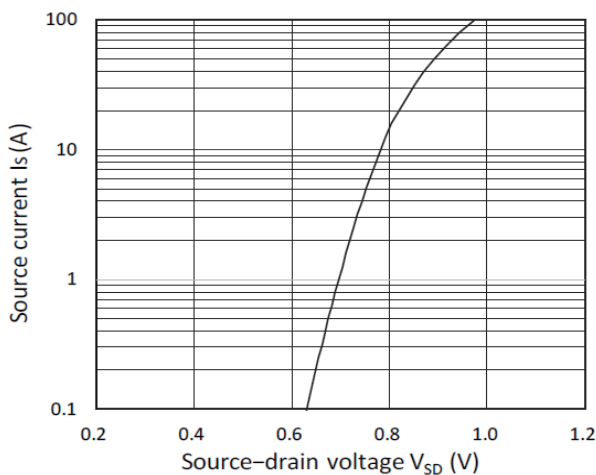


Figure 4: RDS(ON) vs. VGS

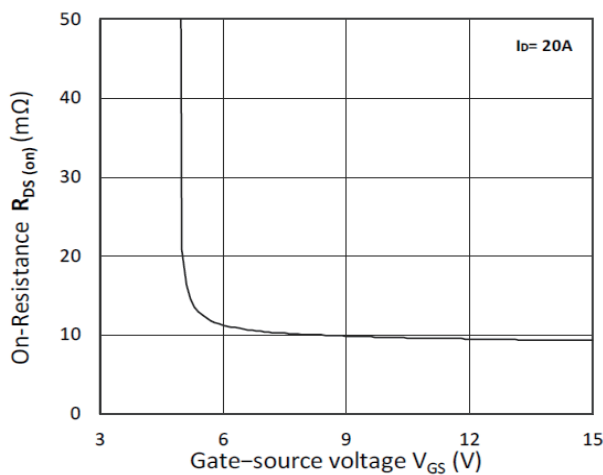


Figure 5: RDS(ON) vs. ID

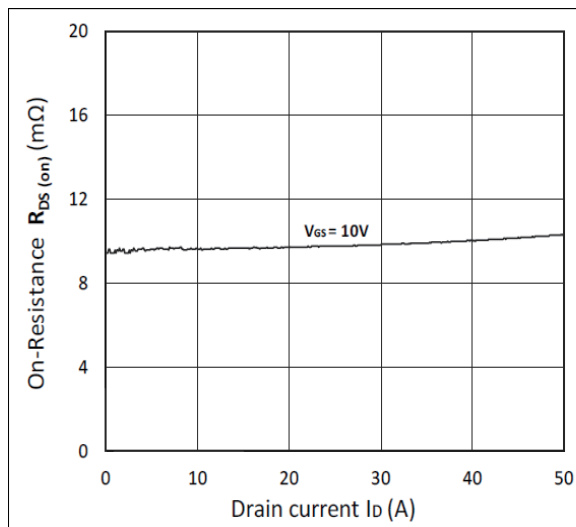
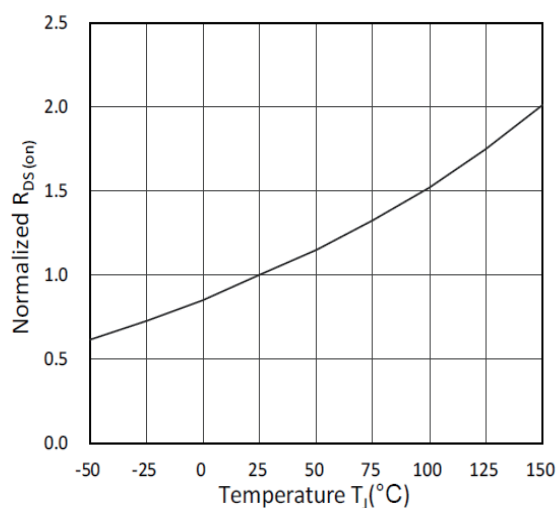


Figure 6: Normalized RDS(on) vs. Temperature



Typical Performance Characteristics

Figure 7: Capacitance Characteristics

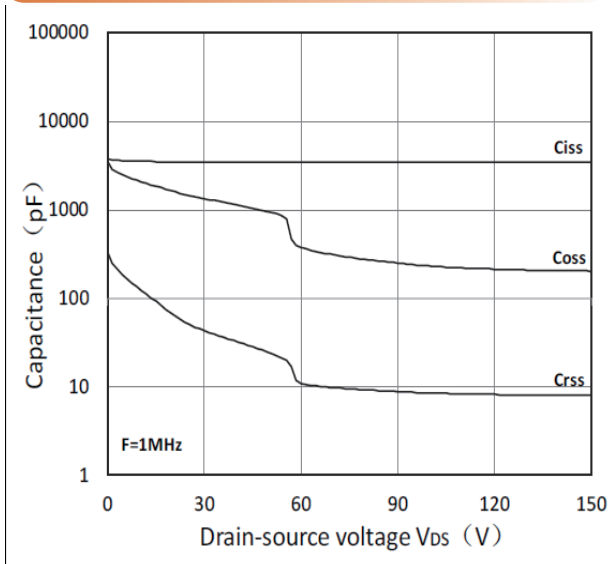


Figure 8: Gate Charge Characteristics

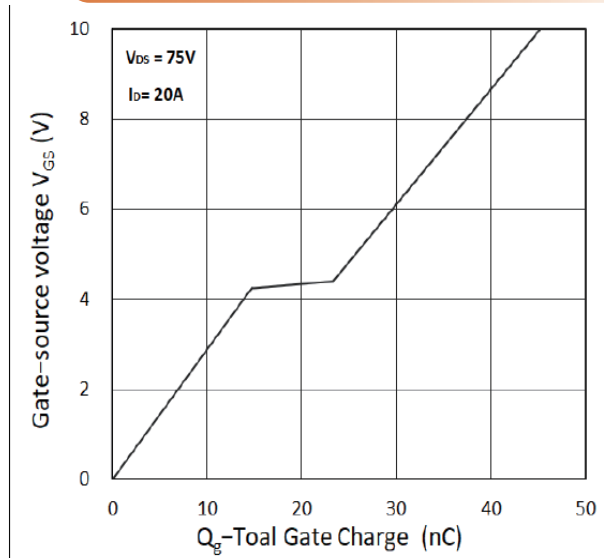


Figure 9: Power Dissipation

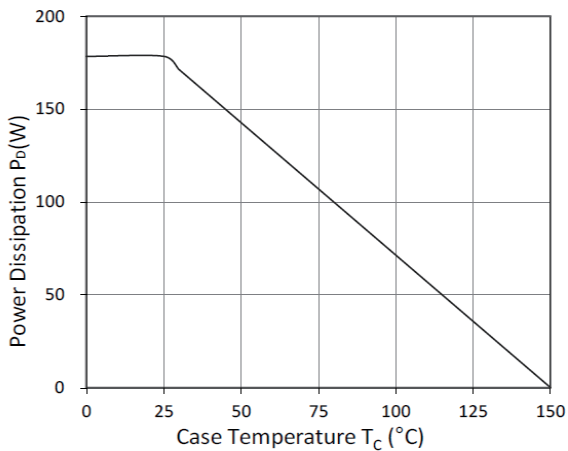


Figure 10: Safe Operating Area

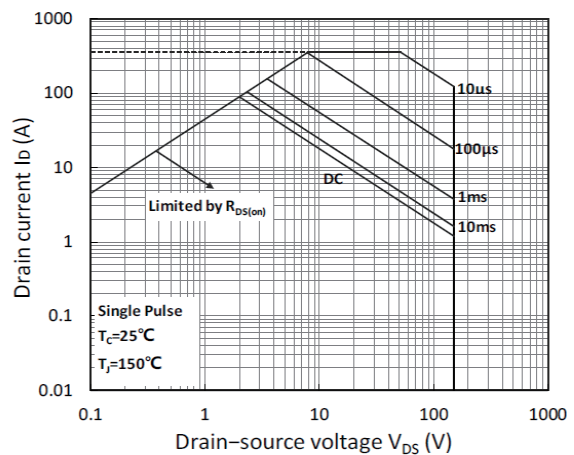
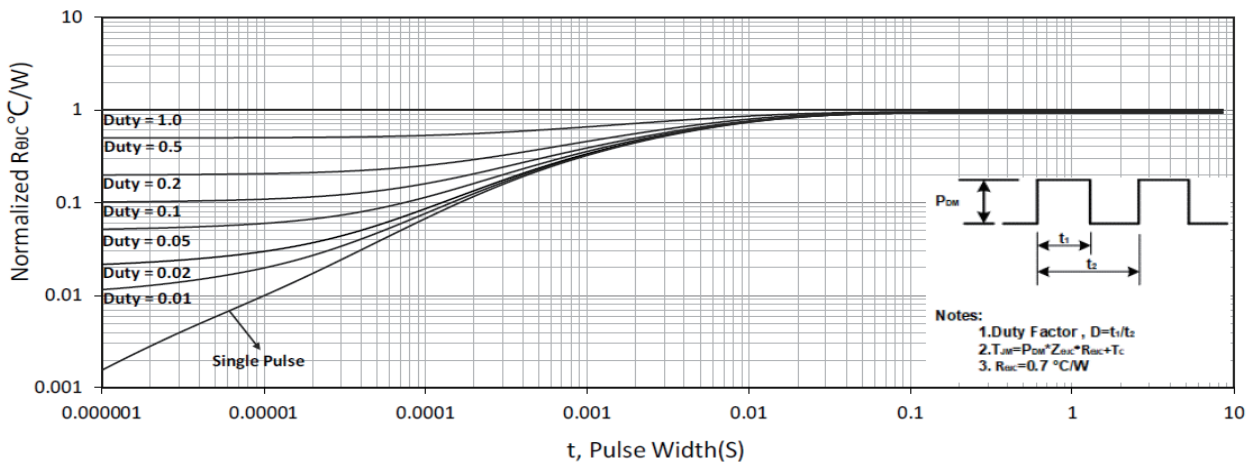


Figure 11: Normalized Maximum Transient Thermal Impedance



Test Circuit

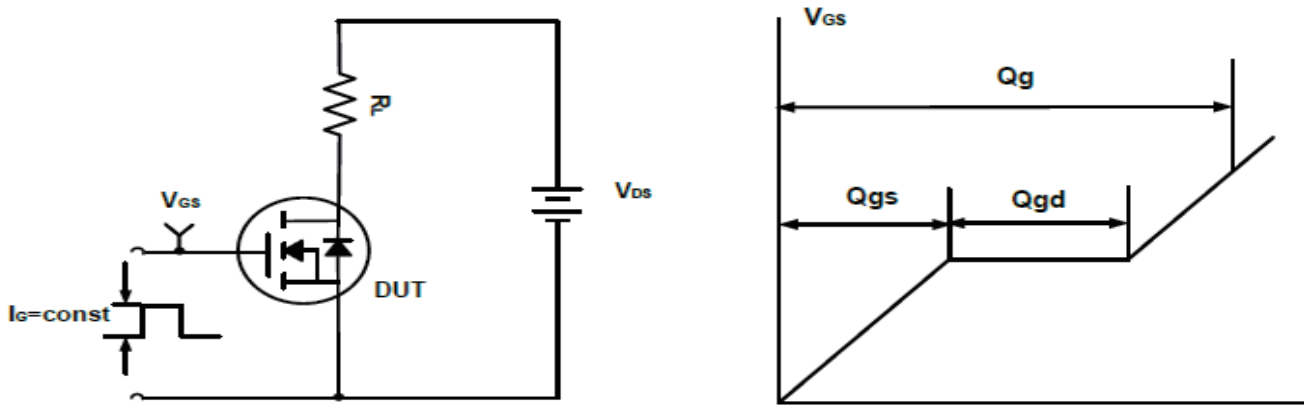


Figure A. Gate Charge Test Circuit & Waveforms

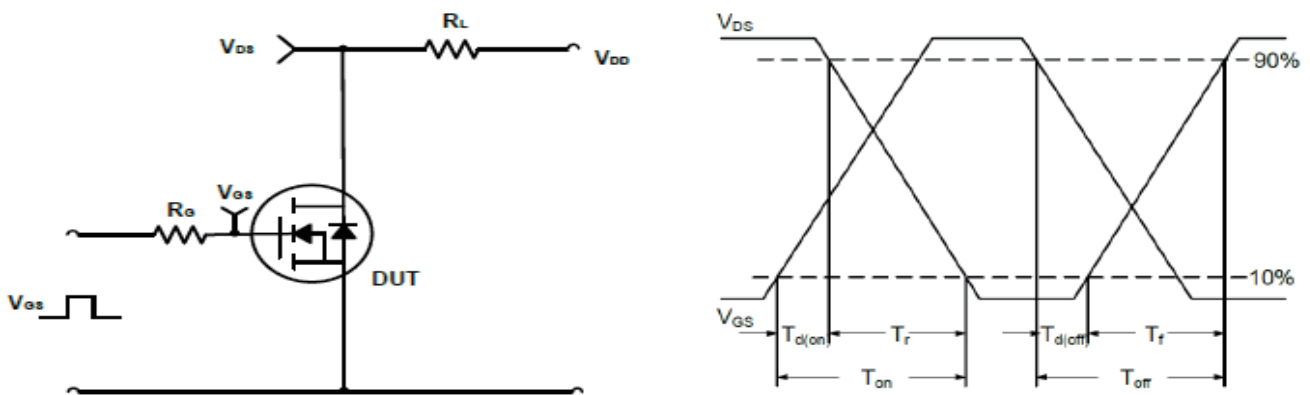


Figure B. Switching Test Circuit & Waveforms

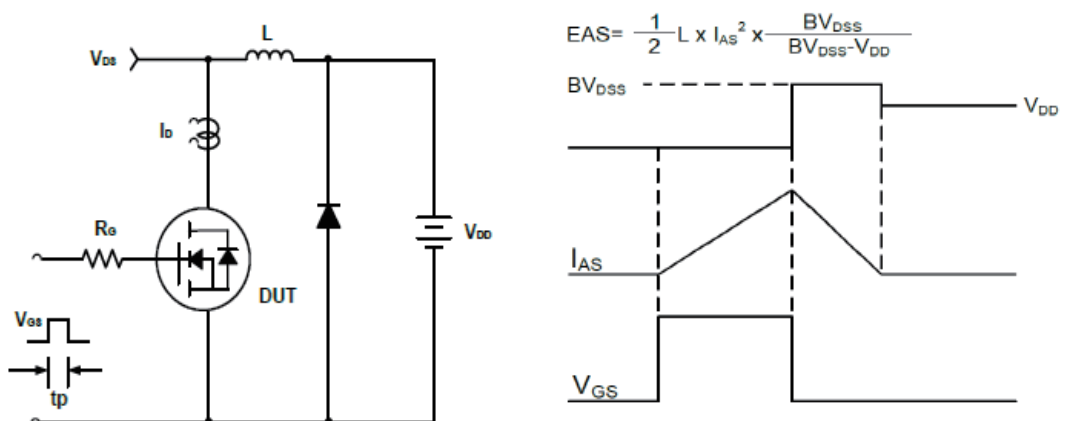
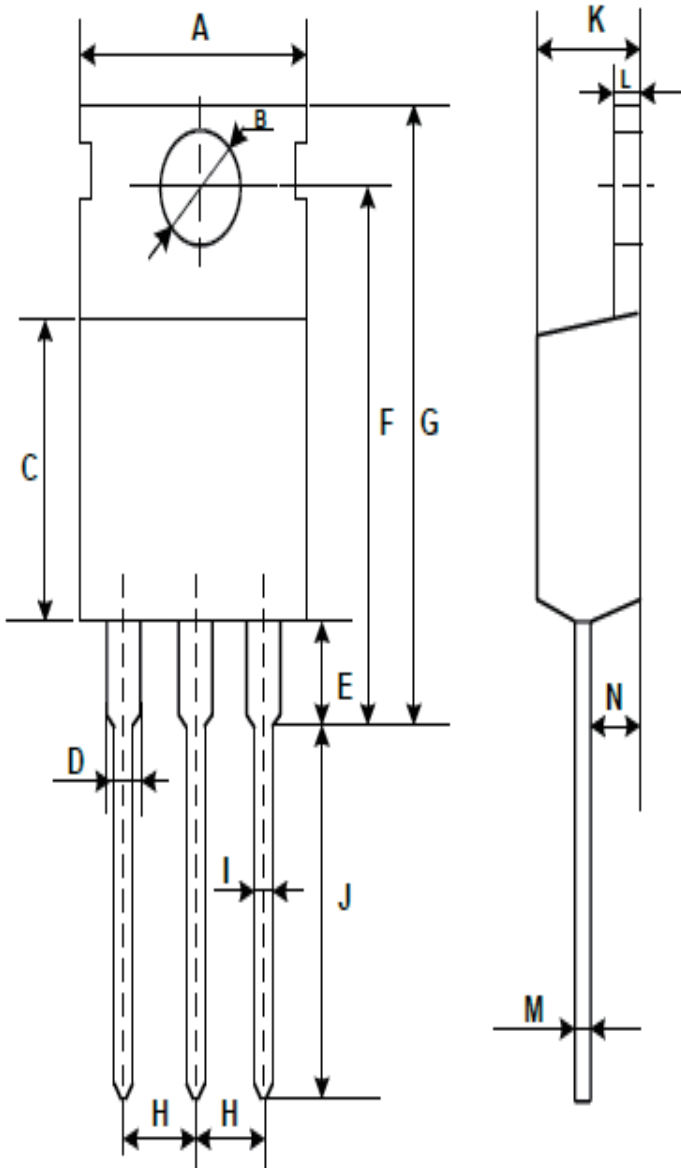


Figure C. Unclamped Inductive Switching Circuit & Waveforms

Mechanical Dimensions for TO-220



COMMON DIMENSIONS

| SYMBOL | MM | |
|--------|----------|------|
| | MIN | MAX |
| A | 9.7 | 10.3 |
| B | 3.4 | 3.8 |
| C | 8.8 | 9.4 |
| D | 1.17 | 1.47 |
| E | 2.6 | 3.5 |
| F | 15.1 | 16.7 |
| G | 19.55MAX | |
| H | 2.54REF | |
| I | 0.7 | 0.95 |
| J | 9.35 | 11 |
| K | 4.3 | 4.77 |
| L | 1.2 | 1.45 |
| M | 0.4 | 0.65 |
| N | 2.2 | 2.6 |